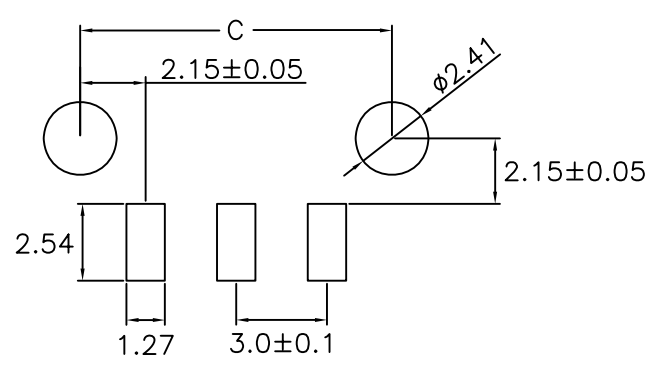
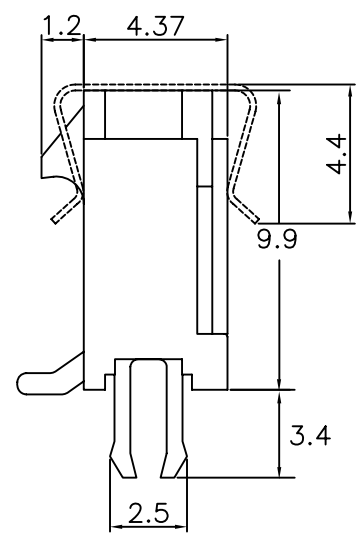
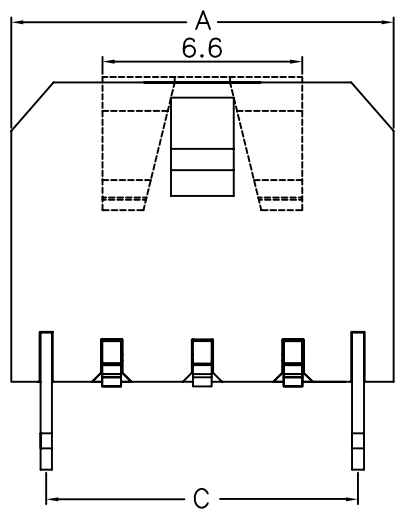
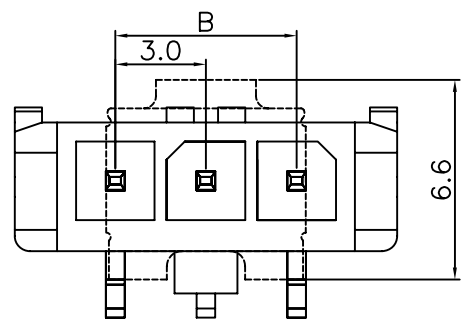


REV.	SPECIFICATION	ECN NO.	APPD.



P.C. Board Layout

Material:

Housing: High Temperature Housing UL94V-0.
 Contact: Copper Alloy.
 Lock: Copper Alloy.

Electrical Characteristics:

Current Rating: 5.0 AMP
 Dielectric Withstanding Voltage: 1500V AC.
 Voltage Rating: 250V DC/AC RMS.
 Insulator Resistance: 1000MΩ min.
 Contact Resistance: 10mΩ max.
 Operating Temperature: -25°C ~ +85°C.

***RoHS Compliant**

4976- 1 X xx T D 3 L T -M
 Series Single No. of T: Tin D: SMD 3: Vertical L: With T: Tape & -M
 Row Position Plated Type Lock Reel Package Pad

Position	2 Thru 12
Dimension	
A	3.00 X No. of Positions+3.65
B	3.00 X (No. of Positions-1)
C	3.00 X No. of Positions+1.3

Tolerances	Drawn No.	4976D01011	Title:	
x = ±0.5	Projection		4976 Series	
.x = ±0.25	Unit	mm	Scale	1:1
.xx = ±0.15	Drawn By	Yun 04/26'11	3.0mm Wafer SMD Vertical	

Ø732

OUPIN
 OUPIN ELECTRONIC(KUNSHAN) CO., LTD.
 P/N: 4976-1XxxTD3LT-M
 SHEET 1/1 Ver.No. B3